6. Pinning information

6.1 Pinning

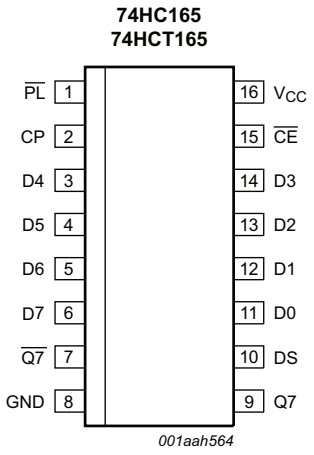
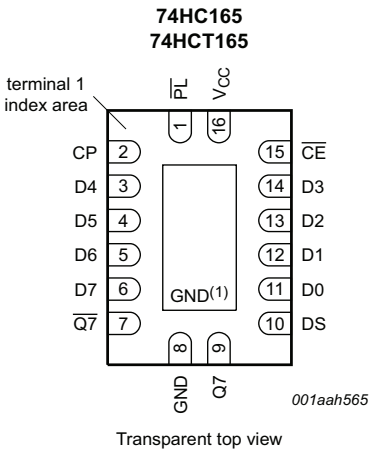


Fig 4. Pin configuration (SO16 and (T)SSOP16)



Transparent top view

(1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration (DHVQFN16)

6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$\overline{PL}$	1	asynchronous parallel load input (active LOW)
CP	2	clock input (LOW-to-HIGH edge-triggered)
$\overline{Q7}$	7	complementary output from the last stage
GND	8	ground (0 V)
Q7	9	serial output from the last stage
DS	10	serial data input
D0 to D7	11, 12, 13, 14, 3, 4, 5, 6	parallel data inputs (also referred to as Dn)
$\overline{CE}$	15	clock enable input (active LOW)
V_{CC}	16	positive supply voltage

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